

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Subbarayudu Mutya</td> <td>05/01/2013</td> </tr> <tr> <td>Debesh Kumar Sahu</td> <td>05/02/2013</td> </tr> <tr> <td>Ling Hang</td> <td>02/04/2013</td> </tr> <tr> <td>Chih-Ping Hsu</td> <td>03/12/2013</td> </tr> <tr> <td>Shawn C. Morrison</td> <td>02/08/2013</td> </tr> <tr> <td>Venkata Appala Naidu Babbadi</td> <td>02/20/2013</td> </tr> <tr> <td>Venkata Raji Reddy Kanthala</td> <td>05/01/2013</td> </tr> </tbody> </table>		Name	Execution Date	Subbarayudu Mutya	05/01/2013	Debesh Kumar Sahu	05/02/2013	Ling Hang	02/04/2013	Chih-Ping Hsu	03/12/2013	Shawn C. Morrison	02/08/2013	Venkata Appala Naidu Babbadi	02/20/2013	Venkata Raji Reddy Kanthala	05/01/2013
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<table border="1"> <tr> <td>Name:</td> <td>QUALCOMM Incorporated</td> </tr> <tr> <td>Street Address:</td> <td>5775 Morehouse Drive</td> </tr> <tr> <td>City:</td> <td>San Diego</td> </tr> <tr> <td>State/Country:</td> <td>CALIFORNIA</td> </tr> <tr> <td>Postal Code:</td> <td>92121</td> </tr> </table>		Name:	QUALCOMM Incorporated	Street Address:	5775 Morehouse Drive	City:	San Diego	State/Country:	CALIFORNIA	Postal Code:	92121						
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CORRESPONDENCE DATA																	
Fax Number: 8586582502 <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i> Email: us-docketing@qualcomm.com Correspondent Name: QUALCOMM Incorporated Address Line 1: 5775 Morehouse Drive Address Line 4: San Diego, CALIFORNIA 92121																	
ATTORNEY DOCKET NUMBER:	111924																
NAME OF SUBMITTER:	Lisa Nodarse																

CH \$40.00 13355767

Signature:	/Lisa Nodarse/
Date:	05/13/2013
Total Attachments: 21 source=111924_ASST_2013_05_13_SIGNED#page1.tif source=111924_ASST_2013_05_13_SIGNED#page2.tif source=111924_ASST_2013_05_13_SIGNED#page3.tif source=111924_ASST_2013_05_13_SIGNED#page4.tif source=111924_ASST_2013_05_13_SIGNED#page5.tif source=111924_ASST_2013_05_13_SIGNED#page6.tif source=111924_ASST_2013_05_13_SIGNED#page7.tif source=111924_ASST_2013_05_13_SIGNED#page8.tif source=111924_ASST_2013_05_13_SIGNED#page9.tif source=111924_ASST_2013_05_13_SIGNED#page10.tif source=111924_ASST_2013_05_13_SIGNED#page11.tif source=111924_ASST_2013_05_13_SIGNED#page12.tif source=111924_ASST_2013_05_13_SIGNED#page13.tif source=111924_ASST_2013_05_13_SIGNED#page14.tif source=111924_ASST_2013_05_13_SIGNED#page15.tif source=111924_ASST_2013_05_13_SIGNED#page16.tif source=111924_ASST_2013_05_13_SIGNED#page17.tif source=111924_ASST_2013_05_13_SIGNED#page18.tif source=111924_ASST_2013_05_13_SIGNED#page19.tif source=111924_ASST_2013_05_13_SIGNED#page20.tif source=111924_ASST_2013_05_13_SIGNED#page21.tif	

ASSIGNMENT

WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
3. Ling Hang, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
4. Chih-Ping Hsu, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
5. Shawn C. Morrison, a citizen of The United States of America, having a mailing address located at 6180 Spine Road, Boulder, CO, 80301, and a resident of Boulder, CO,
6. Venkata Appala Naidu Babbadi, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
7. Venkata Raji Reddy Kanthala, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at HYDERABAD, on 1st MAY, 2013 MSR
LOCATION DATE Subbarayudu Mutya

Done at _____, on _____
LOCATION DATE Debesh Kumar Sahu

Done at _____, on _____
LOCATION DATE Ling Hang

Done at _____, on _____
LOCATION DATE Chih-Ping Hsu

Done at _____, on _____
LOCATION DATE Shawn C. Morrison

Done at _____, on _____
LOCATION DATE Venkata Appala Naidu Babbadi

Done at _____, on _____
LOCATION DATE Venkata Raji Reddy Kanthala

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WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
3. Ling Hang, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
4. Chih-Ping Hsu, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
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7. Venkata Raji Reddy Kanthala, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011. Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Subbarayudu Mutya

Done at Hyderabad, IN, on 05-02-2013
LOCATION DATE Debesh Kumar Sahu

Done at _____, on _____
LOCATION DATE Ling Hang

Done at _____, on _____
LOCATION DATE Chih-Ping Hsu

Done at _____, on _____
LOCATION DATE Shawn C. Morrison

Done at _____, on _____
LOCATION DATE Venkata Appala Naidu Babbadi

Done at _____, on _____
LOCATION DATE Venkata Raji Reddy Kanthala

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WHEREAS, WE,

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3. Ling Hang, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
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6. Venkata Appala Naidu Babbadi, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
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have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Subbarayudu Mutya

Done at _____, on _____
LOCATION DATE Debesh Kumar Sahu

Done at San Diego, USA, on 2/4/2013
LOCATION DATE Ling Hang

Done at _____, on _____
LOCATION DATE Chih-Ping Hsu

Done at _____, on _____
LOCATION DATE Shawn C. Morrison

Done at _____, on _____
LOCATION DATE Venkata Appala Naidu Babbadi

Done at _____, on _____
LOCATION DATE Venkata Raji Reddy Kanthala

ASSIGNMENT

WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
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have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

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NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

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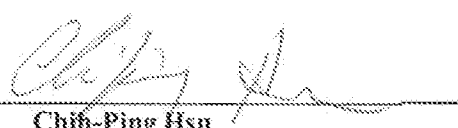
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Done at _____, on _____
LOCATION DATE Subharayudu Mutya

Done at _____, on _____
LOCATION DATE Debesh Kumar Sahu

Done at _____, on _____
LOCATION DATE Ling Hang

Done at San Diego, on 3/12/13
LOCATION DATE 
Chih-Ping Hsu

Done at _____, on _____
LOCATION DATE Shawn C. Morrison

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ASSIGNMENT

WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
3. Ling Hang, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
4. Chih-Ping Hsu, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
5. Shawn C. Morrison, a citizen of The United States of America, having a mailing address located at 6180 Spine Road, Boulder, CO, 80301, and a resident of Boulder, CO,
6. Venkata Appala Naidu Babbadi, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
7. Venkata Raji Reddy Kanthala, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE,

its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Subbarayudu Mutya

Done at _____, on _____
LOCATION DATE Debesh Kumar Sahu

Done at _____, on _____
LOCATION DATE Ling Hang

Done at _____, on _____
LOCATION DATE Chih-Ping Hsu

Done at Boulder, USA, on 2/8/2013
Colorado LOCATION DATE 
Shawn C. Morrison

Done at _____, on _____
LOCATION DATE Venkata Appala Naidu Babbadi

Done at _____, on _____
LOCATION DATE Venkata Raji Reddy Kanthala

ASSIGNMENT

WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
3. Ling Hang, a citizen of The United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121, and a resident of San Diego, CA,
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6. Venkata Appala Naidu Babbadi, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
7. Venkata Raji Reddy Kanthala, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **MOBILE DEVICE TUNE AWAY PERIODS** (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Subbarayudu Mutya

Done at _____, on _____
LOCATION DATE Debesh Kumar Sahu

Done at _____, on _____
LOCATION DATE Ling Hang

Done at _____, on _____
LOCATION DATE Chih-Ping Hsu

Done at _____, on _____
LOCATION DATE Shawn C. Morrison

Done at Hyderabad, India, on 20th Feb 2012
LOCATION DATE Venkata Appala Naidu Babbadi

Done at _____, on _____
LOCATION DATE Venkata Raji Reddy Kanthala

ASSIGNMENT

WHEREAS, WE,

1. Subbarayudu Mutya, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
2. Debesh Kumar Sahu, a citizen of India, having a mailing address located at Bldg 9, 15th floor Mindspace HiTec City Rd, Hyderabad 500081 and a resident of Hyderabad, Andhra Pradesh, India,
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5. Shawn C. Morrison, a citizen of The United States of America, having a mailing address located at 6180 Spine Road, Boulder, CO, 80301, and a resident of Boulder, CO,
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WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

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its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No(s). 13/355,767 filed January 23, 2012, Qualcomm Reference No. 111924, and all provisional applications relating thereto together with U.S. Provisional Application No(s). 61/498,881, filed June 20, 2011, Qualcomm Reference No. 111924P1 (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide

PATENT

OFFICE COMM. No. 111924

Page 3 of 3

all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY represent that WE have full and exclusive, unencumbered right to sell, assign, convey and transfer all subject matter herein, and hereby covenant that WE have not and will not execute any writing or do any act whatsoever conflicting with these presents.

Done at Hyderabad on 1st May 1943 Subbarayudu Mutya
LOCATION DATE

Done at _____ on _____ Devesh Kumar Sahu
LOCATION DATE

Done at _____ on _____ Ling Hang
LOCATION DATE

Done at _____ on _____ Chih-Ping Hsu
LOCATION DATE

Done at _____ on _____ Shawn C. Morrison
LOCATION DATE

Done at _____ on _____ Venkata Appala Naidu Bahhadi
LOCATION DATE

Done at Hyderabad on 1st May 1943 Venkata Raji Reddy Kunthala
LOCATION DATE

PATENT

RECORDED: 05/13/2013

REEL: 030403 FRAME: 0437